PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Teck Kheng Lee

**Serial No.:** Not Yet Assigned

**Filed:** March 12, 2004

**For:** INNOVATIVE SOLDER BALL PAD STRUCTURE TO EASE DESIGN RULE, METHODS OF FABRICATING SAME AND SUBSTRATES, ELECTRONIC DEVICE ASSEMBLIES AND SYSTEMS EMPLOYING SAME

**Confirmation No.:** Unknown

**Examiner:** Unknown

**Group Art Unit:** Unknown

**Attorney Docket No.:** 2269-5351.1US
(02-0239.01/US)

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV325782482US

Date of Deposit with USPS: March 12, 2004

Person making Deposit: Christopher Haughton

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The present application is a continuation of application Serial No. 10/230,962, filed August 29, 2002, pending.

Pursuant to M.P.E.P. 2001.06(b), the Examiner is respectfully requested to consider the information of record in the prior application, and to confirm in the first Office Action on the merits that such art has in fact been reviewed. A PTO-1449 form listing all of the information of record in the prior application is enclosed herewith.

This Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. 1.17(p) is required.

Respectfully submitted,

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Telephone: 801-532-1922

Date: March 12, 2004
TNB/ps:ljb

Enclosures: Form PTO-1449

Document in ProLaw

| Form PTO-1449<br>INFORMATION DISCLOSURE CITATION IN AN APPLICATION<br>*(Use several sheets if necessary)* | Docket Number (Optional)<br>**2269-5351.1US (02/0239.01/US)** | Application Number<br>**Not Yet Assigned** |
|---|---|---|
| | Applicant **Teck Kheng Lee** | |
| | Filing Date **March 12, 2004** | Group Art Unit **Unknown** |

## U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
|---|---|---|---|---|---|---|
| | 3,392,442 | 07/1968 | Napier et al. | | | |
| | 5,767,010 | 06/1998 | Mis et al. | | | |
| | 5,773,359 | 06/1998 | Mitchell et al. | | | |
| | 5,872,399 | 02/1999 | Lee | | | |
| | 6,107,180 | 08/2000 | Munroe et al. | | | |
| | 6,111,321 | 08/2000 | Agarwala | | | |
| | 6,201,305 B1 | 03/2001 | Darveaux et al. | | | |
| | 6,249,044 B1 | 06/2001 | Kao et al. | | | |
| | 6,316,828 B1 | 11/2001 | Tao et al. | | | |
| | 6,399,417 B1 | 06/2002 | Lee et al. | | | |
| | 6,404,064 B1 | 06/2002 | Tsai et al. | | | |

## FOREIGN PATENT DOCUMENTS

| | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | Translation YES | Translation NO |
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## OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

| | | |
|---|---|---|
| | | http://www.maxim-ic.com/1st_pages/UCSP.htm, "Wafer-Level Chip-Scale Package," Dallas Semiconductor, date unknown, 10 pages. |
| | | "CSP Present and Future," date unknown, 3 pages. |
| | | TARTER et al., "Ball Grid Array Performance Characteristics; A User's Design Guide," File Creation Date: March 31, 1999. |

| EXAMINER | DATE CONSIDERED |
|---|---|
| | |

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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## OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

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|---|---|---|
| | | "BGA (Ball Grid Array)," National Semiconductor Corporation, September 1999, pp. 1-7, Application Note 1126. |
| | | MicroStar BGA Packaging Reference Guide, September 1999, 15 pages, Literature Number: SSYZ015B. |
| | | "Mounting Technology," Sharp, File Creation Date: October 10, 2000, pp. 12-36. |
| | | "Chapter 7: Board Design and Layout Considerations," FBGA User's Guide, April 12, 2002, pp. 41-45, Version 4.1. |

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| | |

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